

#### Single-supply linear-output temperature sensor in bare die form

Rev 1.1 28/04/20

#### Description

The LM335A precision linear-output temperature sensor is designed for simple calibration and ease of use. Output is derived from an integrated 2-terminal Zener with a breakdown voltage directly proportional to absolute temperature at  $10 \text{mV}/^\circ \text{K}$ . Calibrated at  $+25^\circ \text{C}$ , the LM335A has a typical accuracy of  $0.5^\circ \text{C}$  over a wide -40°C to  $100^\circ \text{C}$  temperature range. With less than  $1\Omega$  dynamic impedance, performance is consistent across a current range of  $450 \mu \text{A}$  to 5mA. The device suits use as a general purpose sensor where its small size, low impedance and linear output enables simple circuit integration.

#### **Ordering Information**

The following part suffixes apply:

No suffix - MIL-STD-883 /2010B Visual Inspection

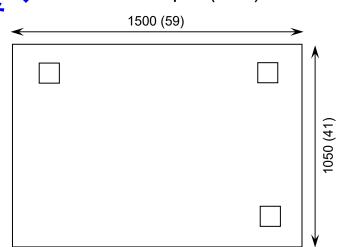
For High Reliability versions of this product please see

LM135 and LM135/

## Features:

- Wide temperature range: -40 to +1000
- 0.5% typical accuracy at 25°C
- Single-point calibration for high orecision
- Operates from 450µA t. 5m
- <1Ω dynamic impedance</li>
- Linear output
- Small size of high integration.

#### Die Dimensions in µm (mils)



### Supply Formats:

- Default Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape On request
- Unsawn Wafer On request
- Die Thickness <> 350µm(14 Mils) On request
- Assembled into Hermetic Package On request

#### **Mechanical Specification**

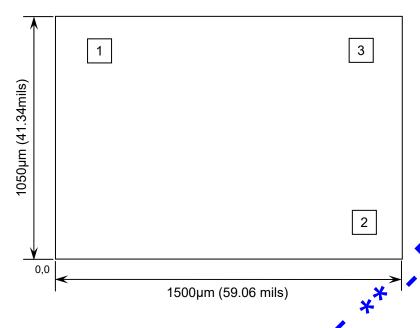
Die Size (Unsawn)	1500 x 1050 59 x 41	µm mils	
Minimum Bond Pad Size	104 x 104 4.09 x 4.09	μm mils	
Die Thickness	350 (±20) 13.78 (±0.79)	μm mils	
Top Metal Composition	Al 1%Si 1.1µm		
Back Metal Composition	N/A – Bare Si		





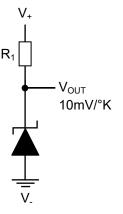
#### Rev 1.1 28/04/20

### Pad Layout and Functions



PAD	FUNCTION	COORDINATES (µn			COORDINATES (H	4 <b>ገ</b> ፫ኖ (μm)
1 75	TONOTION	Х	Υ			
1	V+	<b>131</b>	848			
2	V-	1201	103			
3	ADJ	1268	848			
CONNECT CHIP BACK TO V- OR FLOAT						

### Simplified Schematic



### Calibration methodology and schematic

The LM335A response is proportional to absolute temperature with the extrapolated output of sensor going to 0V at 1. K (-273.15°C). Errors in output voltage versus temperature are only slope. Thus a calibration of the slope at one temperature corrects errors at an temperatures. The circuit output (calibrated or not) is given by the equation:

$$VOUT_T + VOUT_{To} \times \frac{T}{T_o}$$

#### Where:

- T is the unknown temperature
- To is the reference temperature (in °K).

Nominally, the output is calibrated at 10mV/°K.



Self-heating can decrease accuracy; LM335A should be operated at low current but sufficient enough to drive the sensor and calibration circuit to the maximum operating temperature. If used in surroundings where the thermal resistance is constant, the errors due to self-heating can be externally calibrated. This is possible if the circuit is biased with a temperature stable current. Heating will then be proportional to Zener voltage and therefore temperature. In this way, the error due to self-heating is proportional to the absolute temperature as scale factor errors.



V<sub>OUT</sub> 10mV/°K

10kΩ\*

\* Calibrated for

2.982V at 25°C



### Absolute Maximum Ratings<sup>1</sup>

Rev 1.1 28/04/20

PARAMETER	SYMBOL	VA	UNIT			
Reverse Current	I <sub>R</sub>	15		15		I A
Forward Current	l <sub>F</sub>	1	mA			
Operating Temperature	T <sub>OPER</sub>	Continuous -40 to +100		<b>°</b> C		
Storage Temperature	T <sub>STG</sub>	-65 to +150		°C		

<sup>1.</sup> Operation above the absolute maximum rating may cause device failure. Operation at the absolute maximum ratings, for extended periods, may reduce device reliability.

#### **Recommended Operating Conditions**

PARAMETER		SYMBOL	MIN	MAX	UNITS
Temperature	Continuous	T <sub>A</sub>	-40	100	°C
Forward Current		I <sub>F</sub>	0.45	5	mA

### Temperature Parameters<sup>2</sup> (T<sub>A</sub> = 25°C unless therwise specified)

PARAMETER	SYMBOL	CONDITIONS		LIMITS		UNITS
I ANAMETER	STMBOL	CONDITIONS	MIN	TYP	MAX	ONITO
Output Voltage	V <sub>OUT</sub>	$T_J = 25$ C, $V_R = 1$ mA	2.95	2.98	3.01	V
Un-calibrated	$\Delta T_1$	$T_A = 25^{\circ}C$ , $I_R = 1mA$	-	1	3	°C
Temperature Error	$\Delta T_2$	-40°C< T <sub>A</sub> ≤ 100°C,I <sub>R</sub> = 1mA	-	2	5	°C
25°C Calibrated Temperature Error	$\Delta T_3$	-40°C≤T <sub>A</sub> ≤ +100°C,I <sub>R</sub> = 1mA	-	0.5	1	°C
Non-linearity	$\Delta T_4$	40°C≤ T <sub>A</sub> ≤ +100°C,I <sub>R</sub> = 1mA	-	0.3	1.5	°C

### Electrical Parameters<sup>2</sup> (T<sub>A</sub> = 25°C unless otherwise specified)

PARAMETER	SYMBOL	CONDITIONS		LIMITS		UNITS
PARAMETER	4 I MIBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output voltage change with our ent	ΔV <sub>OUT</sub>	450μA ≤ I <sub>R</sub> ≤ 5mA, Constant temperature	-	3	14	mV
Dynamic mredance	$\Delta R_1$	$T_J = 25^{\circ}C, I_R = 1mA$	-	0.6	-	Ω
Temperature coefficient of output voltage	тс	T <sub>J</sub> = 25°C, I <sub>R</sub> = 1mA	-	+10	-	mV/°C
		Still air	-	80	-	
Time constant	$   au_{T}  $	Air 0.5m/s	-	10	-	s
	Stirred oil	-	1	-		
Time stability	T <sub>STAB</sub>	T <sub>J</sub> = 125°C	-	0.2	-	°C/1000h

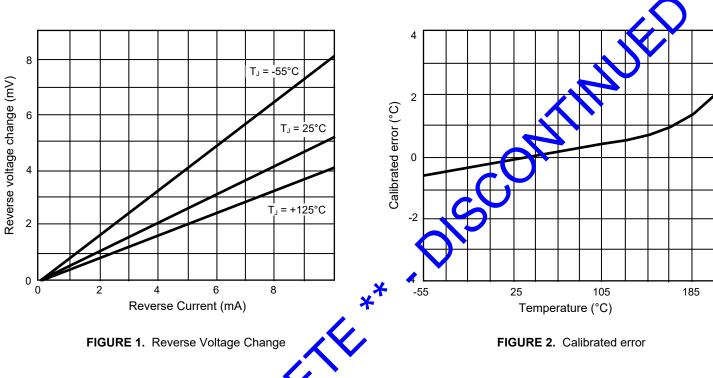
<sup>2.</sup> Accuracy measurements are made in a well-stirred oil bath. For other conditions, self-heating must be considered.





Rev 1.1 28/04/20

### Typical Characteristics (T<sub>J</sub> = 25°C unless otherwise specified)



T<sub>J</sub> = -55°C

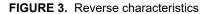
T<sub>J</sub> = -55°C

T<sub>J</sub> = -55°C

T<sub>J</sub> = -125°C

T<sub>J</sub> = +125°C

Reverse Voltage (V)



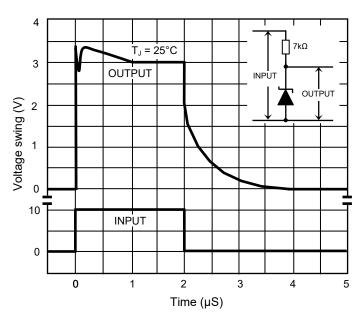


FIGURE 4. Response time





Rev 1.1 28/04/20

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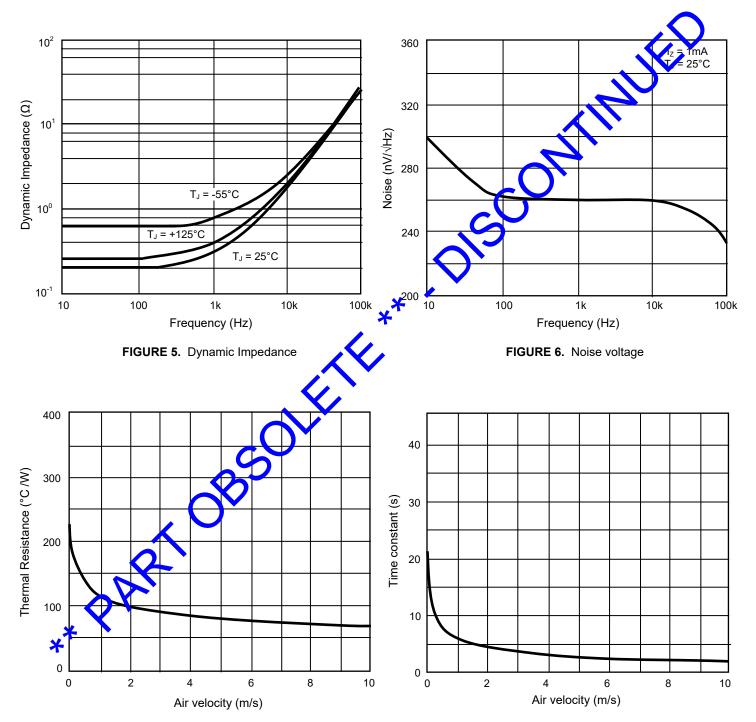


FIGURE 8. Thermal resistance, junction-to-air

FIGURE 9. Thermal time constant





Rev 1.1 28/04/20

### Typical Characteristics (T<sub>J</sub> = 25°C unless otherwise specified)

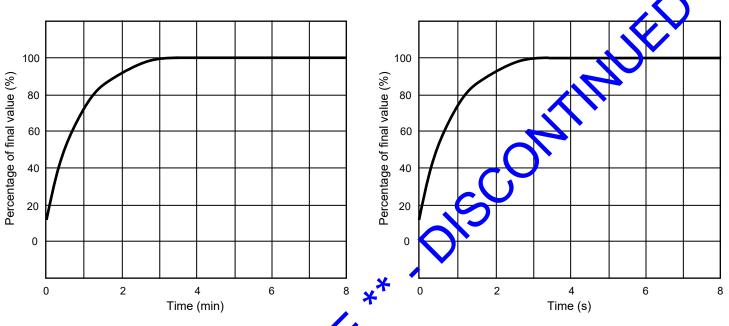


FIGURE 10. Thermal response in still air

FIGURE 11. Thermal response in stirred-oil bath

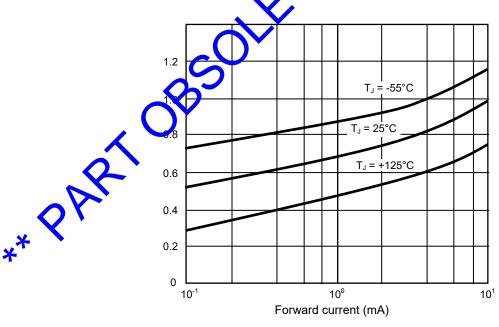


FIGURE 12. Forward characteristics





### **Typical Applications**

Rev 1.1 28/04/20

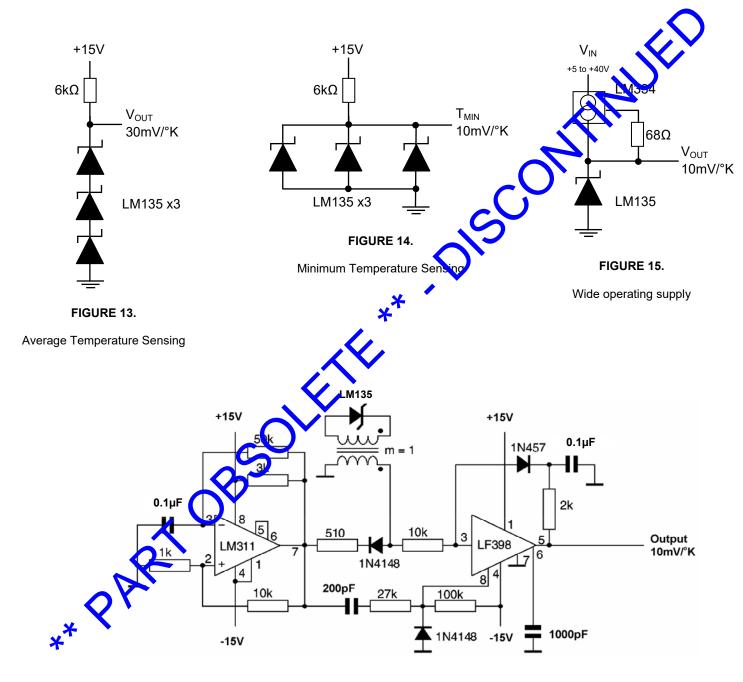


FIGURE 16.

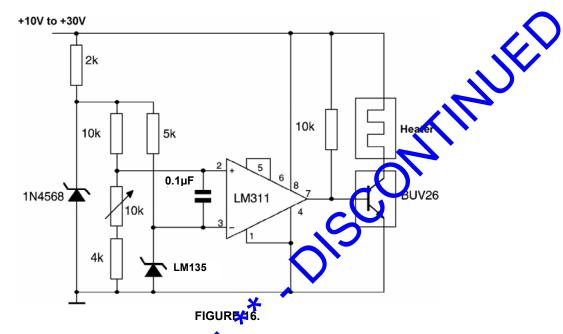
Isolated Temperature Sensor





Rev 1.1 28/04/20

### Typical Applications continued



Temperature Controller 1k +15V +15V +15V 200k 12k 12k 6k +15V 20k LM308 Output 10mV/°C Output LM308 10mV/°C 20k 10k LM135 -15V 180k 📥 100pF LM135 100pF 50k \*Adjust for 2.7315V at output of LM308

FIGURE 17.

Centigrade Thermometer

FIGURE 18.

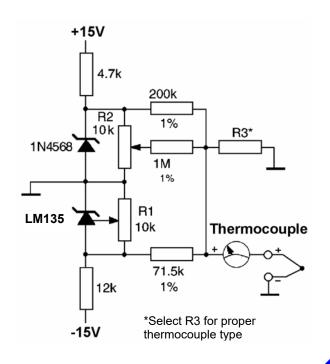
Differential Temperature Sensor





#### Rev 1.1 28/04/20

### Thermocouple compensation



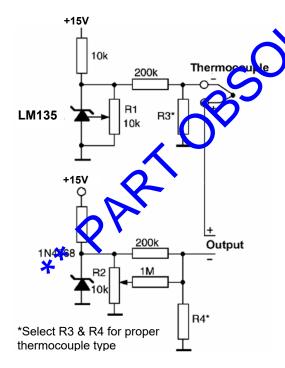
Thermocouple	R3	SEEBECK Coefficient
J	377Ω	52.3µ //°C
Т	308Ω	42.8 JV/°C
K	293Ω	40.8μV/°C
S	45.30	6.4μV/°C

#### Adjustments:

- 1. Short 1N4568.
- 2. Adjust R1 for SEEBECK coefficient times ambient temperature in degrees Kelvin across R3.
- 3. Short M135 and adjust R2 for voltage across R3 corresponding to thermocouple type as below:

* TJ	14.32mV	K	11.17mV
T	11.9mV	S	1.768mV

FIGURE 19. Thermocouple cold junction compensation (compensation for grounded thermocouple)



Thermocouple	R3	R4	SEEBECK Coefficient
J	1.05kΩ	365Ω	52.3µV/°C
Т	856Ω	315Ω	42.8µV/°C
K	816Ω	300Ω	40.8µV/°C
S	128Ω	46.3Ω	6.4µV/°C

#### Adjustments:

- 1. Adjust R1 for the voltage across R3 equal to the SEEBECK coefficient times ambient temperature in degrees Kelvin.
- 2. Adjust R2 for voltage across R4 corresponding to the thermocouple as below:

J 14.32mV K 11.17mV T 11.9mV S 1.768mV

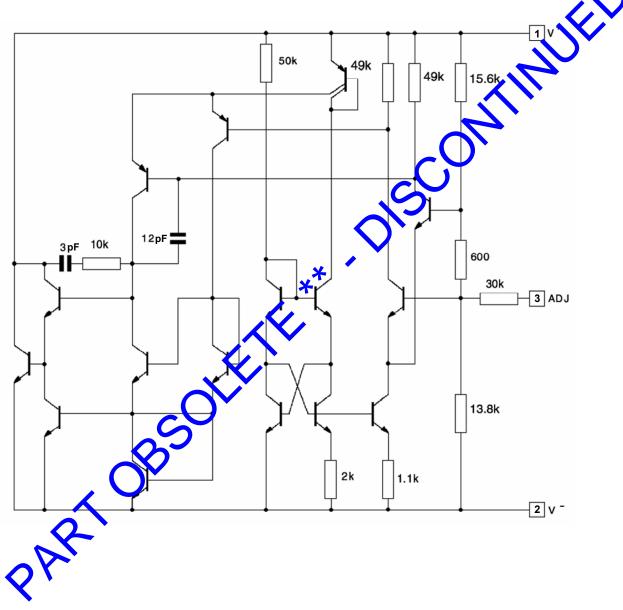
FIGURE 20. Single power supply cold junction compensation





Circuit schematic

Rev 1.1 28/04/20



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